



*Alpha Zeta Delta of Chi Psi Fraternity*  
**Temple Hoyne Buell Memorial Scholarship**  
**Official Application**

In the memory of our beloved brother Temple Hoyne Buell, ZΔ 1916, three scholarships, each worth \$1,000, are being offered to qualified incoming freshmen men to the University of Illinois. This scholarship is offered to incoming freshmen men without regard to race, creed, color or religion. Acceptance into the membership of the fraternity is not required. The scholarship will be paid in a single amount of \$1,000 in the Fall 2023 semester upon proof of full-time enrollment at the University of Illinois. Recipients will be those applicants who best exemplify the ideals of Chi Psi Fraternity intellectually, morally, and socially.

Semifinalists will be announced on June 1, 2023, and will be required to attend an interview at a time and place to be announced, or *via* Zoom. Finalists will be selected following the first round of interviews. Each finalist will then be required interview with a panel of members of the Alumni Scholarship Committee during the first week of school at the Chi Psi Lodge, located at 710 West Ohio Street, Urbana, Illinois. Scholarship winners may be announced informally or at an awards banquet to be held in September, 2023.

Name: \_\_\_\_\_

Address: \_\_\_\_\_  
\_\_\_\_\_

Phone #: \_\_\_\_\_

Email: \_\_\_\_\_

H.S. GPA: \_\_\_\_\_

Expected Major: \_\_\_\_\_  
\_\_\_\_\_

Have you been accepted into the University of Illinois?

Yes \_\_\_\_\_ No \_\_\_\_\_ Wait List \_\_\_\_\_

**Please list all of your extracurricular activities (athletics, clubs, etc.), hobbies and interests, and indicate whether you served in any positions of leadership:**

\_\_\_\_\_

**Please list all of those ways in which you provided service to your community:**

\_\_\_\_\_

Please submit this completed application, along with an official copy of your high school transcript, by email to BuellScholarship@gmail.com, or by U.S. Mail to Chi Psi Fraternity, 16863 S. Corinne Cir., Plainfield, Illinois 60586. The application deadline is **May 28, 2023** – all applications must be postmarked or received electronically by that date.